

Band Switching Diode

- **Applications**

High frequency switching

- **Features**

- 1) Small surface mounting type.
- 2) High reliability.

- **Construction**

Silicon epitaxial planar



L1SS356T1



SOD- 323

Driver Marking

L1SS356T1 = B

Absolute maximum ratings ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Limits	Unit
DC reverse voltage	V_R	35	V
DC forward current	I_F	100	mA
Junction temperature	T_j	125	$^{\circ}\text{C}$
Storage temperature	T_{stg}	-55~+125	$^{\circ}\text{C}$

Electrical characteristics ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	—	—	1.0	V	$I_F=10\text{mA}$
Reverse current	I_R	—	—	10	nA	$V_R=25\text{V}$
Capacitance between terminals	C_T	—	—	1.2	pF	$V_R=6\text{V}$, $f=1\text{MHz}$
Forward operating resistance	r_F	—	—	0.9	Ω	$I_F=2\text{mA}$, $f=100\text{MHz}$

Electrical characteristic curves

($T_A=25^\circ\text{C}$)

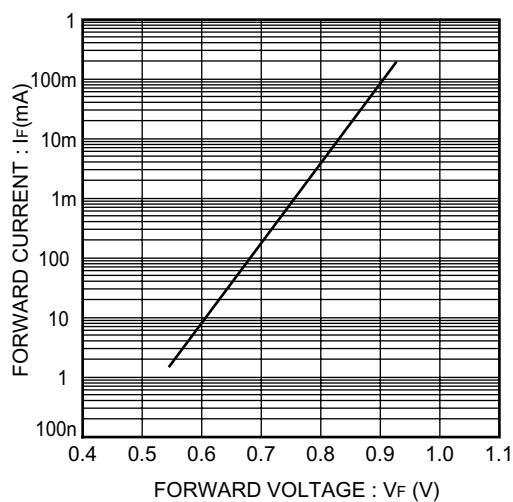


Fig. 1 Forward characteristics

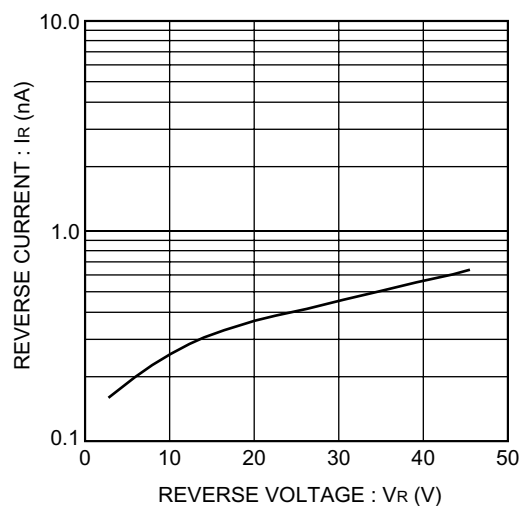


Fig. 2 Reverse characteristics

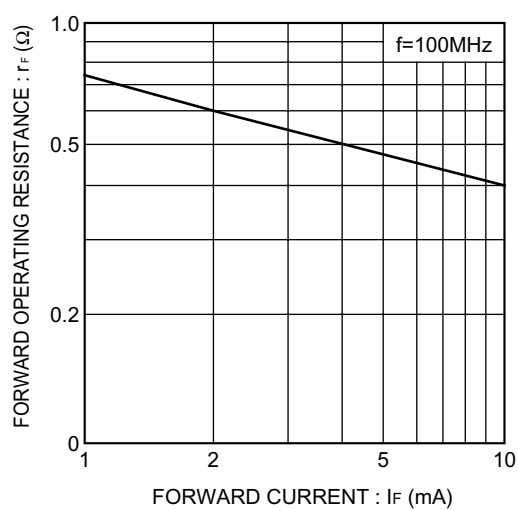


Fig. 4 Forward operating resistance characteristics

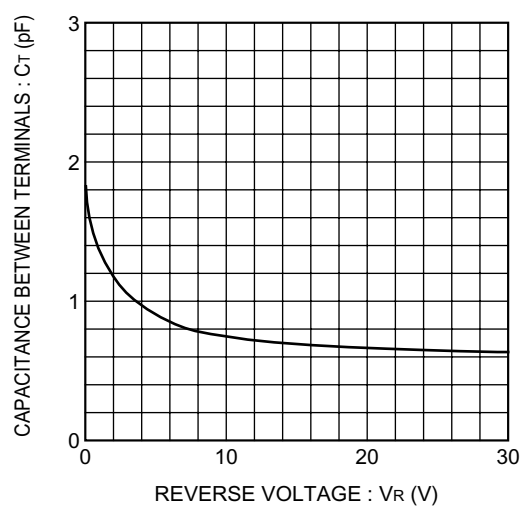


Fig. 3 Capacitance between terminals characteristics

L1SS356T1

PACKAGE DIMENSIONS

SOD-323

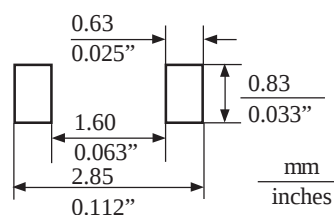
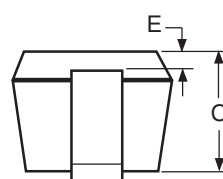
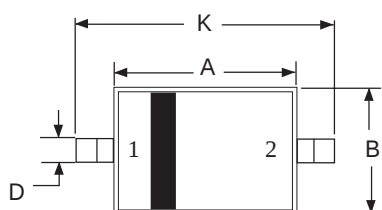
PLASTIC PACKAGE

CASE 477-02

ISSUE B



SOD-323



NOTES:

1. CONTROLLING DIMENSION: MILLIMETERS
2. LEAD THICKNESS SPECIFIED PER L / F DRAWING WITH SOLDER PLATING.

DIN	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.60	1.80	0.063	0.071
B	1.15	1.35	0.045	0.053
C	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
E	0.15 REF		0.006 REF	
H	0.00	0.10	0.0000	0.004
J	0.089	0.177	0.0035	0.0070
K	2.30	2.7	0.091	0.106

STYLE 1:
PIN 1: CATHODE
2: ANODE